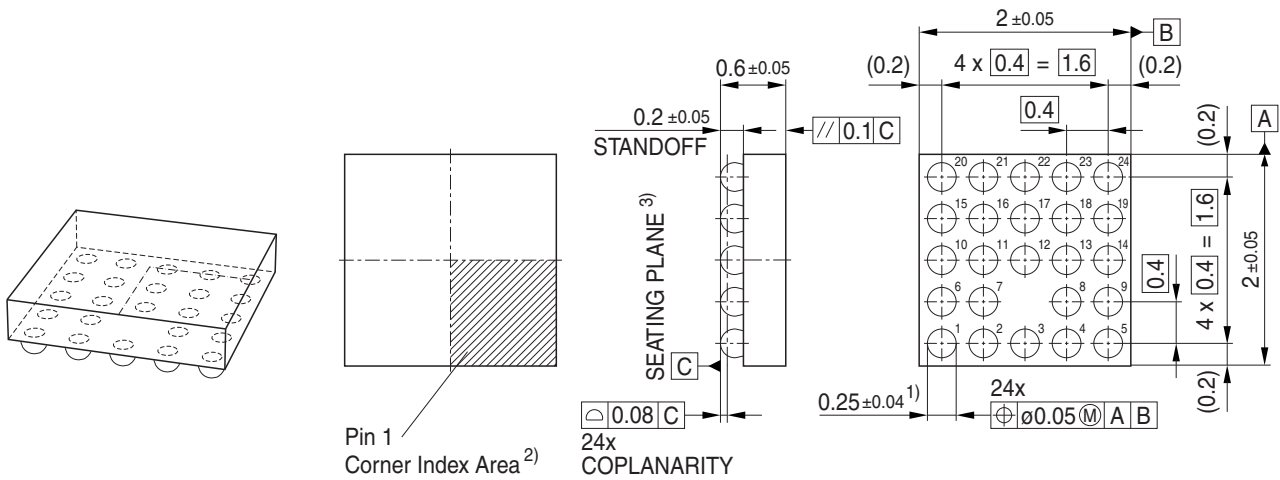


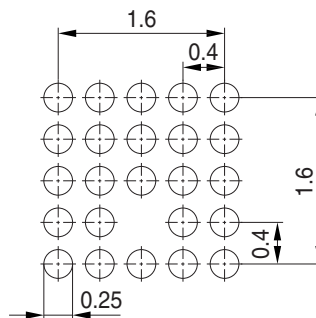
Package Outline



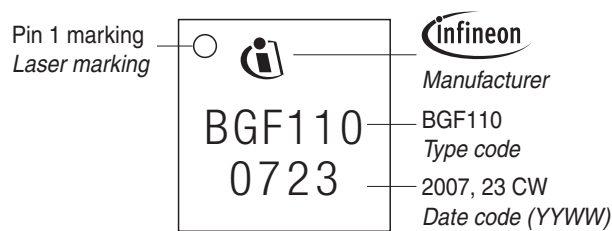
- 1) Dimension is measured at the maximum solder ball diameter, parallel to primary datum C
- 2) Pin 1 corner identified by marking
- 3) Primary datum C and seating plane are defined by the spherical crowns of the balls

Foot Print

Soldering Type: Reflow Soldering

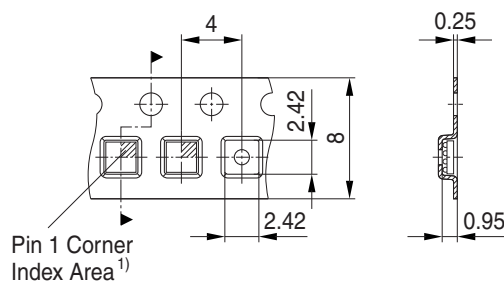


Marking Layout (Example)



Tape and Reel

Reel ϕ 180 mm: 3.000 Pieces/Reel
Reels/Box: 1



- 1) Balls face down